

Product Change Notification / LIAL-02XWMF227

	_	ı	_	_
	а	T	Δ	•
u	a	L.	┖	_

09-Jan-2023

Product Category:

Linear Comparators, Linear Op Amps, Power Management - System Supervisors/Voltage Detectors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5129 Final Notice: Qualification of G700 as a new molding compound material and NiPdAuAg with roughened as a new lead frame DAP surface prep for selected MIC7300, MIC2778, MIC833, and MIC2779 device families available in 5L SOT23 package assembled at STAR assembly site.

Affected CPNs:

LIAL-02XWMF227_Affected_CPN_01092023.pdf LIAL-02XWMF227_Affected_CPN_01092023.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700 as a new molding compound material and NiPdAuAg with roughened as a new lead frame DAP surface prep for selected MIC7300, MIC2778, MIC833, and MIC2779 device families available in 5L SOT23 package assembled at STAR assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	Stars Microelectronics (Thailand) Public Company Limited (STAR)	Stars Microelectronics (Thailand) Public Company Limited (STAR)			
Wire Material	Au	Au			
Die Attach Material	84-1LMISR4	84-1LMISR4			
Molding Compound Material	G600	G700			
Lead-Frame Material	C194	C194			
Lead Frame DAP Surface	NiPdAu with Roughened	NiPdAuAg with Roughened			
Prep	See Pre and Post Change Summary for comparison.				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying G700 mold compound material and NiPdAuAg with Roughened as a new lead frame die attach paddle (DAP) surface prep.

Change Implementation Status:In Progress

Estimated First Ship Date: January 31, 2023 (date code: 2305)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	May 2022					January 2023					
Workweek	1 9	2	2 1	2 2	2 3	>	0 1	0 2	0	0 4	0 5
Initial PCN Issue Date	Х										
Qual Report Availability								Х			
Final PCN Issue Date								Х			
Estimated Implementation Date											х

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 05, 2022: Issued initial notification.

January 09, 2023: Issued final notification. Attached is the qualification report and added estimated first ship date by January 31,2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-02XWMF227_Qual Report.pdf PCN_LIAL-02XWMF227_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

LIAL-02XWMF227 - CCB 5129 Final Notice: Qualification of G700 as a new molding compound material and NiPdAuAg with roughened as a new lead frame DAP surface prep for selected MIC7300, MIC2778, MIC833, and MIC2779 device families available in 5L SOT23 package assembled at STAR assembly site.

Affected Catalog Part Numbers (CPN)

MIC7300YM5-TR

MIC7300YM5-TX

MIC2778-1YM5-TR

MIC2778-2YM5-TR

MIC833YM5-TR

MIC2779H-1YM5-TR

MIC2779H-2YM5-TR

MIC2779L-1YM5-TR

MIC2779L-2YM5-TR

Date: Sunday, January 08, 2023